

N-Channel Super Junction Power MOSFET $\, \mathrm{I\!V}$

General Description

The series of devices use advanced trench gate super junction technology and design to provide excellent RDS(ON) with low gate charge. This super junction MOSFET fits the industry's AC-DC SMPS requirements for PFC, AC/DC power conversion, and industrial power applications.

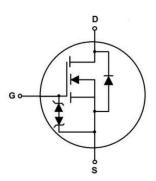
Features

- Optimized body diode reverse recovery performance
- ●Low on-resistance and low conduction losses
- Small package
- ●Ultra Low Gate Charge cause lower driving requirements
- ●100% Avalanche Tested
- ROHS compliant

Application

- Power factor correction (PFC)
- Switched mode power supplies(SMPS)
- Uninterruptible Power Supply (UPS)
- LLC Half-bridge

| V _{DS min@Tjmax} | 750 | V |
|---------------------------|------|----|
| R _{DS(ON)TYP} . | 330 | mΩ |
| I_D | 10.5 | Α |
| Qg | 19.3 | nC |



Schematic diagram

Package Marking And Ordering Information

| Device | Device Package | Marking | |
|-----------|----------------|-----------|--|
| NCE70N380 | TO-220-3L | NCE70N380 | |



TO-220

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Table 1. Absolute Maximum Ratings (T_c=25℃)

| Parameter | Symbol | Value | Unit |
|---|----------------------------------|----------|------|
| Drain-Source Voltage (V _{GS} =0V) | V _{DS} | 700 | V |
| Gate-Source Voltage (VDS=0V) ,AC (f>1 Hz) | Vgs | ± 30 | V |
| Gate-Source Voltage (VDS=0V) ,DC | Vgs | ±20 | V |
| Continuous Drain Current at Tc=25°C | I _{D (DC)} | 10.5 | Α |
| Continuous Drain Current at Tc=100°C | I _{D (DC)} | 7.35 | Α |
| Pulsed drain current (Note 1) | I _{DM (pluse)} | 31.5 | Α |
| Maximum Power Dissipation(Tc=25℃) | P _D | 107 | W |
| Derate above 25°C | | 0.71 | W/°C |
| Single pulse avalanche current (Note 2) | I _{AS} | 1.4 | A |
| Reverse diode dv/dt, $V_{DS} \leq 480 \text{ V,I}_{SD} < I_{D}$ | dv/dt | 15 | V/ns |
| Drain Source voltage slope,V _{DS} ≤480 V | dv/dt | 50 | V/ns |
| Operating Junction and Storage Temperature Range | T _J ,T _{STG} | -55+175 | °C |

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Table 2. Thermal Characteristic

| Parameter | Symbol | Value | Unit |
|---|-------------------|-------|-------|
| Thermal Resistance, Junction-to-Case (Maximum) | R _{thJC} | 1.40 | °C /W |
| Thermal Resistance, Junction-to-Ambient (Maximum) | R _{thJA} | 62 | °C /W |

Table 3. Electrical Characteristics (TA=25°Cunless otherwise noted)

| Parameter | Symbol | Condition | Min | Тур | Max | Unit |
|--|---------------------|---|-----|------|------|------|
| On/off states | | | | | | |
| Drain-Source Breakdown Voltage | BV _{DSS} | V _{GS} =0V I _D =250uA | 700 | | | V |
| Zero Gate Voltage Drain Current(Tc=25°ℂ) | I _{DSS} | V _{DS} =700V,V _{GS} =0V | | | 1 | μA |
| Zero Gate Voltage Drain Current(Tc=125℃) | I _{DSS} | V _{DS} =700V,V _{GS} =0V | | | 50 | μA |
| Gate-Body Leakage Current | I _{GSS} | V _{GS} =±20V,V _{DS} =0V | | | ±200 | nA |
| Gate Threshold Voltage | V _{GS(th)} | V _{DS} =V _{GS} ,I _D =250uA | 3 | | 4 | V |
| Drain-Source On-State Resistance | R _{DS(ON)} | V _{GS} =10V, I _D =5.5A | | 330 | 390 | mΩ |
| Dynamic Characteristics | | | | | | |
| Gate Resistance | Rg | F=1MHZ, D-S short | | 18 | | Ω |
| Input Capacitance | C _{lss} | V 50VVV 0V | | 850 | | pF |
| Output Capacitance | Coss | V_{DS} =50V, V_{GS} =0V, | | 29 | | pF |
| Reverse Transfer Capacitance | C _{rss} | F=1MHz | | 3.4 | | pF |
| Total Gate Charge | Qg | | | 19.3 | | nC |
| Gate-Source Charge | Q _{gs} | V _{DS} =520V,I _D =5.5A, V _{GS} =10V | | 2.8 | | nC |
| Gate-Drain Charge | Q_{gd} | | | 9.2 | | nC |
| Gate plateau voltage | Vgp | | | 4.2 | | V |
| Switching times | | | | | | |
| Turn-on Delay Time | t _{d(on)} | | | 12 | | nS |
| Turn-on Rise Time | t _r | V _{DD} =520V,I _D =5.5A, | | 7 | | nS |
| Turn-Off Delay Time | t _{d(off)} | $R_G=4\Omega,V_{GS}=10V$ | | 48 | | nS |
| Turn-Off Fall Time | t _f | | | 7 | | nS |
| Source- Drain Diode Characteristics | | | | | | |
| Source-drain current(Body Diode) | I _{SD} | T 05%0 | | | 10.5 | Α |
| Pulsed-Source-drain current(Body Diode) | I _{SDM} | T _C =25°C | | | 31.5 | Α |
| Forward on voltage | V _{SD} | Tj=25°C,I _{SD} =10.5A,V _{GS} =0V | | 0.9 | 1.1 | V |
| Reverse Recovery Time | t _{rr} | | | 205 | | nS |
| Reverse Recovery Charge | Qrr | Tj=25°C,I _F 5.5A, | | 0.92 | | uC |
| Peak reverse recovery current | I _{rrm} | di/dt=100A/µs | | 9 | | Α |

Notes: 1. Repetitive Rating: Pulse width limited by maximum junction temperature

2. Tj=25 $^{\circ}\text{C}$,VDD=50V,VG=10V, RG=25 Ω



TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS (curves)

Figure 1. Safe operating area

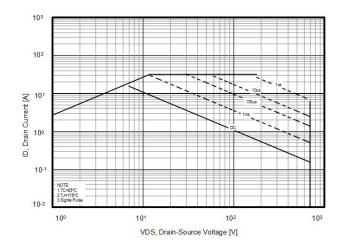


Figure 2. Source-Drain Diode Forward Voltage

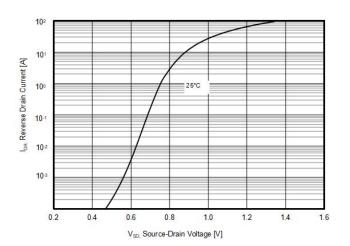


Figure 3. Output characteristics

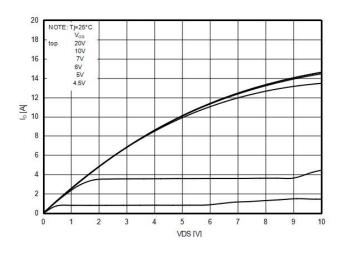


Figure 4. Transfer characteristics

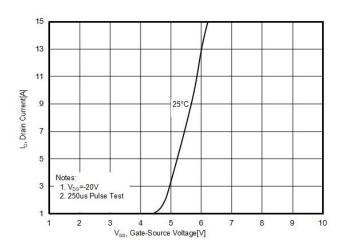


Figure 5. Static drain-source on resistance

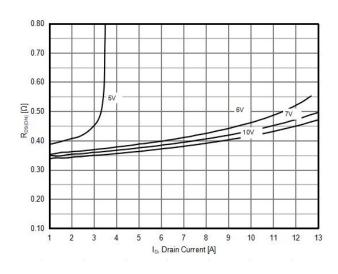
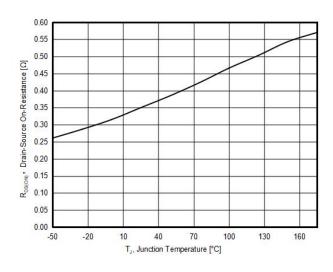


Figure 6. RDS(ON) vs Junction Temperature



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Figure 7. BV_{DSS} vs Junction Temperature

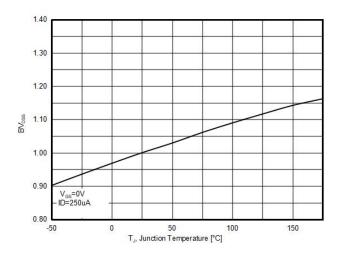


Figure 9. Gate charge waveforms

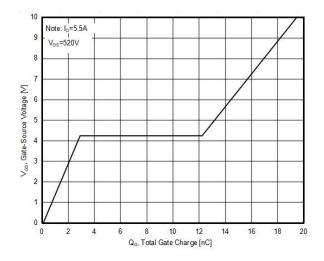


Figure 8. Maximum I_D vs Junction Temperature

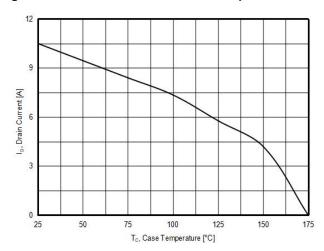
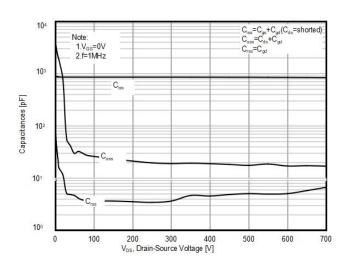


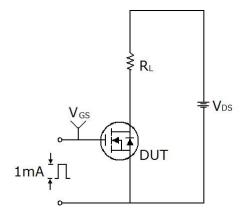
Figure 10. Capacitance

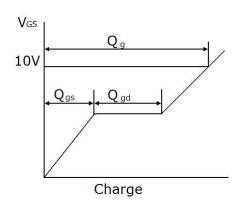




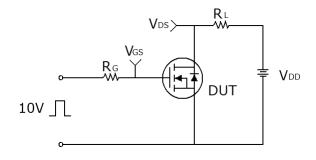
Test circuit

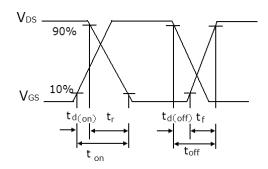
1) Gate charge test circuit & Waveform



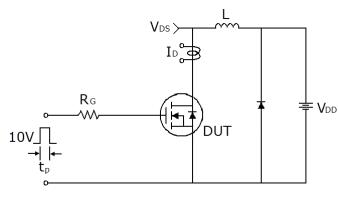


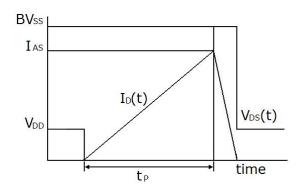
2) Switch Time Test Circuit:





3) Unclamped Inductive Switching Test Circuit & Waveforms

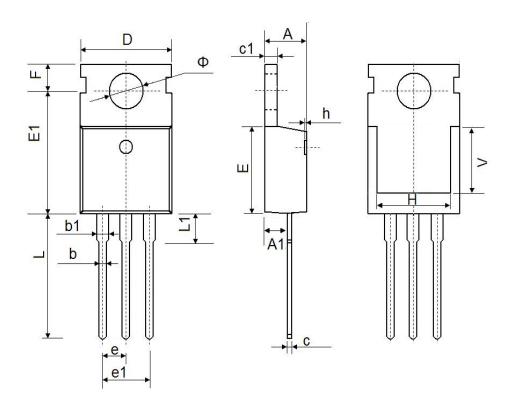




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TO-220-3L-E Package Information



| Symbol | Dimensions | In Millimeters | Dimensions In Inches | | | |
|--------|------------|----------------|----------------------|----------|--|--|
| Зушьог | Min. | Max. | Min. | Max. | | |
| A | 4.20 | 4.60 | 0.165 | 0.181 | | |
| A1 | 2.25 | 2.55 | 0.089 | 0.100 | | |
| b | 0.70 | 0.90 | 0.028 | 0.035 | | |
| b1 | 1.17 | 1.37 | 0.046 | 0.054 | | |
| С | 0.33 | 0.65 | 0.013 | 0.026 | | |
| c1 | 1.20 | 1.40 | 0.047 | 0.055 | | |
| D | 8.95 | 9.75 | 0.352 | 0.384 | | |
| E | 9.74 | 10.04 | 0.352 | 0.384 | | |
| E1 | 9.91 | 10.25 | 0.390 | 0.404 | | |
| е | 2.54 | 2.54BSC | | 0.100BSC | | |
| e1 | 5.08 | 5.08BSC | | 0.200BSC | | |
| Н | 15.45 | 15.85 | 0.608 | 0.624 | | |
| L | 12.90 | 13.40 | 0.508 | 0.528 | | |
| L1 | 2.85 | 3.25 | 0.112 | 0.128 | | |
| Ф | 3.40 | 3.80 | 0.134 | 0.150 | | |



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